Docket No. 1204.45675X00 Serial No. 10/559.684

September 12, 2007

AMENDMENTS TO THE CLAIMS:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

LISTING OF CLAIMS:

25°C.

1. (Currently amended) An adhesive sheet having a property that it can be laminated together with dicing tape onto a wafer prior to stealth dicing, and is capable of being subjected to stealth dicing, and which comprises:, comprising

a polymer component, which includes acrylic rubber having a glass transition temperature of -30° to 50°C, and a weight-average molecular weight of 50,000 to 1,000,000; and

a filler,

wherein the breaking strength of the adhesive sheet in a B-stage state isbeing from 0.1 to 10 MPa at 25°C, and the breaking elongation thereof being from 1 to 40% at

 (Currently amended) <u>TheAn adhesive sheet according to claim 1</u>, comprising a polymer component,

wherein the elastic modulus of the adhesive sheet in a B-stage state isbeing from 1 to 3000 MPa in measurement of the dynamic viscoelasticity at 25°C and 10 Hz, and the elastic modulus thereof being from 4000 to 20000 MPa in measurement of the dynamic viscoelasticity at 25°C and 900 Hz.

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(Currently amended) <u>TheAn</u> adhesive sheet <u>according to claim 1</u>,

comprising a polymer component,

wherein the elastic modulus of the adhesive sheet in a B-stage state isbeing from

1 to 3000 MPa in measurement of the dynamic viscoelasticity at 25°C and 10 Hz, and

the elastic modulus thereof being from 4000 to 20000 MPa in measurement of the

dynamic viscoelasticity at -20°C and 10 Hz.

4. (Currently amended) The adhesive sheet according to claim 12,

comprising the polymer component, and

wherein the elastic modulus of the adhesive sheet in a B-stage state isbeing from

0.1 to 20 MPa in measurement of the dynamic viscoelasticity at 60°C and 10~Hz.

5. and 6. (Cancelled).

7. (Currently amended) The adhesive sheet according to claim 16, wherein

the acrylic rubberthe polymer component, which has a glass transition temperature of-

30 to 50°C and a weight-average molecular weight of 50000 to 1000000, is contained in

an amount of 50% or less of the total weight of the adhesive sheet from which the

weight of a filler is removed.

8. and 9. (Cancelled).

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10. (Previously presented) The adhesive sheet according to claim 1, wherein

the content of remaining volatile matters is from 0.01 to 3% by weight.

11. (Previously presented) The adhesive sheet according to claim 1, which

has a film thickness of 1 to 250 µm.

12. - 43. (Cancelled).

44. (New) The adhesive sheet according to claim 1, wherein the filler is

contained in an amount of 5 to 70% of the total weight of the adhesive sheet.

45. (New) The adhesive sheet according to claim 1, wherein the filler is

contained in an amount of 35% to 60% of the total weight of the adhesive sheet.

46. (New) The adhesive sheet according to claim 1, wherein the acrylic

rubber is contained in an amount of 35% or less of the total weight of the adhesive

sheet from which the weight of a filler is removed.

47. (New) The adhesive sheet according to claim 46, wherein the acrylic

rubber is contained in an amount of from 25% to 35% of the total weight of the adhesive

sheet from which the weight of the filler is removed.

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48. (New) The adhesive sheet according to claim 1, wherein the polymer component further includes epoxy resin.

49. (New) The adhesive sheet according to claim 1, laminated together with the dicing tape onto the wafer, prior to the stealth dicing.